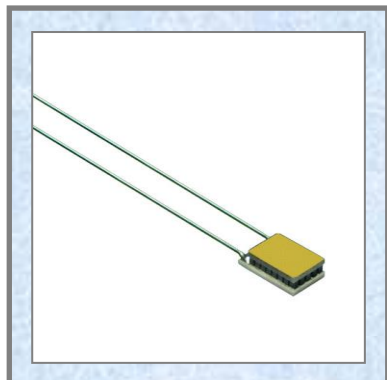


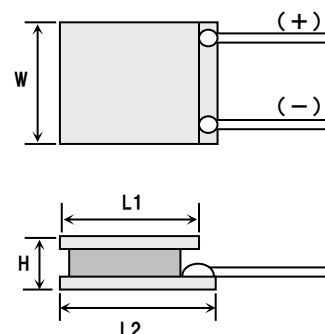
THERMO MODULE DATA

Model **KSAH023** **RoHS 2002/95/EC Compliant**



Th	$\Delta T_{max}(^{\circ}C)$	$I_{max}(A)$	$V_{max}(v)$	$Q_{cmax}(w)$
27°C	74	2.3	3.0	3.3
70°C	92	2.3	3.7	3.6

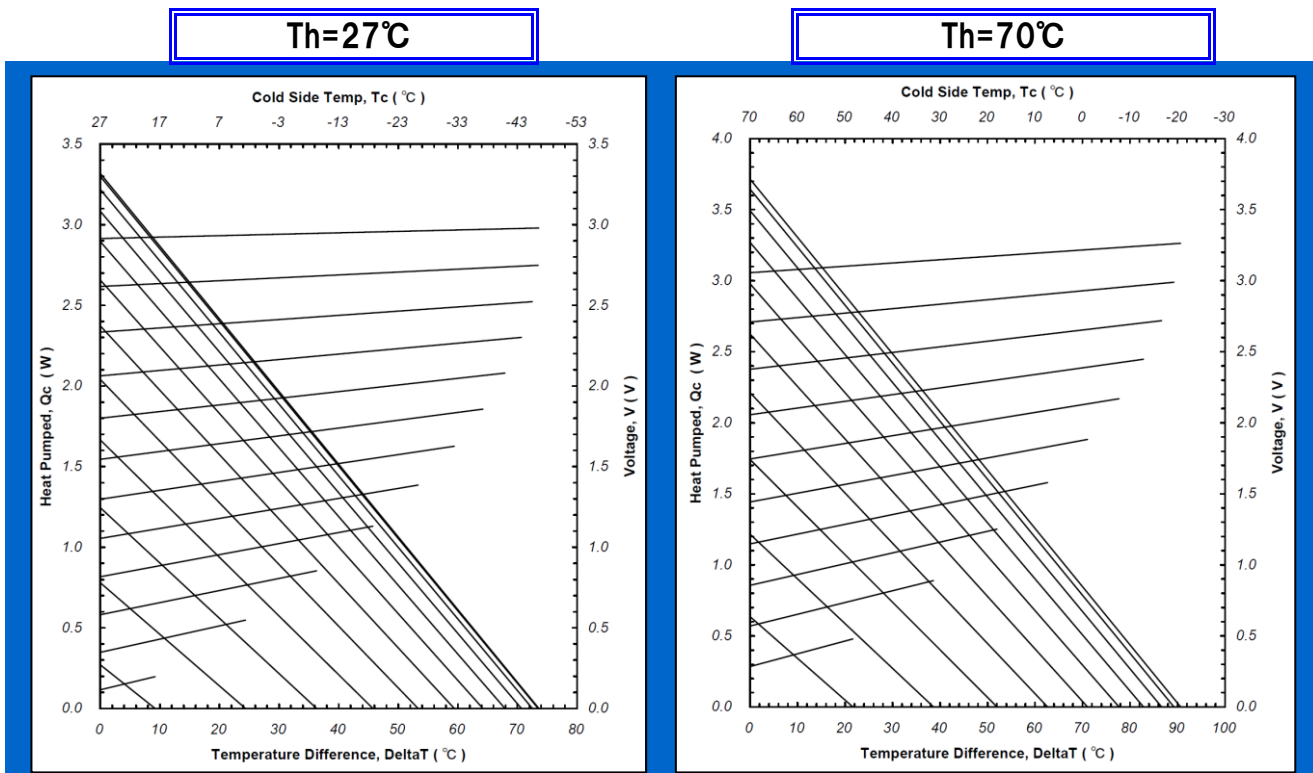
Size(mm)	W	L1	L2	H
Size(mm)	3.8	5.04	6.04	0.97
Tolerance(mm)	± 0.2	± 0.2	± 0.2	± 0.1
Metallization	Cu-Ni-Au			
Ceramic material	Alumina			
Assembly solder	AuSn (melting point:280°C)			



Option

Assembly solder	SnSb (melting point:280°C)
Ceramic material	All models can be assembled with alumina &/or aluminum nitride ceramics.
Pretinning solder	InSn (melting point:117°C), BiSn (melting point:138°C), SnAgCu (melting point:217°C) is also available, when AuSn is selected for assembly solder.

Performance Diagram



Ambient	Nitrogen
Current value	$I = 0.1 \sim 2.3 A$ (Step = 0.10 A)

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